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FOR IMMEDIATE RELEASE

Press Release

YINCAE'S SMT 158A Receives High Praise

(Albany, NY) 05/18/2018 — As chips and packages become more complex, and installed in harsher conditions such as automobiles, the thermal conductivity of underfill materials becomes a greater concern. What can be done to prevent decreased reliability due to thermal dissipation issues? The solution: **SMT 158A**.

SMT 158A has a thermal conductivity of 2 W/mK, at least four times that of conventional underfill materials filled with silicon dioxide. As chips and packages become more complex, and are installed in harsh environments, underfill thermal conductivity becomes an important consideration. An underfill with a high thermal conductivity, such as SMT 158A, reduces heat build up and increases chip reliability. SMT 158A was described by a customer as having a thermal conductivity that is "better than any other UF materials from leading UF suppliers".

SMT 158A is a highly thermally conductive, rapid curing, fast flowing and easily reworked liquid epoxy that can be used for flip chips, chip scale packages, ball grid array devices, package and land grid array applications. It is also suitable for bare chip protection in a variety of advanced packages such as memory cards, chip carriers, hybrid circuits and multi-chip modules. SMT 158A has been designed for a high production environment where process speed and mechanical shock are the key concerns. It is easily dispensed, minimizes induced stresses and provides outstanding reliability performance (e.g., temperature cycling performance) and excellent mechanical resistance.

For more information on YINCAE's SMT 158A underfill, or to learn more about what YINCAE offers, please email us at: info@yincae.com. You can also find more information by visiting our website at: www.yincae.com

Founded in 2005 & headquartered in Albany, New York, YINCAE Advanced Materials is a leading manufacturer and supplier of thermal interface materials, underfill solutions, die attach adhesives, electronic materials, & high-performance coatings used in microchip & optoelectronic devices. YINCAE products provide new technologies to support manufacturing processes from wafer level, to package level, to board level and final devices while facilitating smarter and faster production and supporting green initiatives.

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